



Material Content Data Sheet



Sales Product Name	TLE7268LC			Issued		23. December 2019		
MA#	MA005409739							
Package	PG-TSON-14-3			Weight*		42.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.475	3.51	3.51	35061	35061
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		119	
	non noble metal	zinc	7440-66-6	0.020	0.05		476	
	non noble metal	iron	7439-89-6	0.401	0.95		9519	
	non noble metal	copper	7440-50-8	16.263	38.65	39.66	386505	396619
wire	non noble metal	copper	7440-50-8	0.072	0.17	0.17	1710	1710
encapsulation	organic material	carbon black	1333-86-4	0.045	0.11		1073	
	plastics	epoxy resin	-	2.326	5.53		55273	
	inorganic material	silicondioxide	60676-86-0	20.209	48.01	53.65	480283	536629
leadfinish	non noble metal	tin	7440-31-5	0.621	1.48	1.48	14764	14764
plating	noble metal	silver	7440-22-4	0.091	0.22	0.22	2156	2156
glue	plastics	epoxy resin	-	0.137	0.33		3265	
	noble metal	silver	7440-22-4	0.412	0.98	1.31	9796	13061
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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